

**In the Specification:**

**Please replace the following paragraphs as shown:**

**[0011]** For a better understanding of the invention, reference is made to the attached drawings, wherein:

Fig. 1 is a schematic perspective view of a corrosion-resistive member according to the present invention;

Fig. 2 is a scanning type electron microgram-micrograph of a surface of a test piece in Example 23 after being exposed to a corrosion-withstanding test with chlorine-based gas; and

Fig. 3 is a scanning type electron microgram-micrograph of a sectional surface of a quartz glass piece adjacent to the test piece in Comparative Example 21 after being exposed to NF<sub>3</sub>.

**[0022]** Further, the present inventors noted the purity of the corrosion-resistive member. It is preferable to incorporate an element or elements (including lanthanoids) in Group 2a or 3a in the Periodic Table into the silicon nitride sintered body. These elements are considered to form stable halogen compounds. The ~~lanthanoids-lanthanoid~~ elements include La, Ce, Pr, Nd, Pm, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb and Lu.

**[0023]** Particularly, elements having large atomic weights (heavy) are more preferable (Ca, Sr, Ba, Y and ~~lanthanoids-lanthanoid~~ elements). When an ~~elementone~~ or more elements from Group 2a and 3a ~~is-or~~ are incorporated, the weight reduction of the corrosion-resistive member is reduced.

**[0024]** Among these elements, at least one element selected from the group consisting of calcium, strontium, barium, magnesium, yttrium and ~~lanthanoids-lanthanoid~~ elements is more preferable. Further, at least one element selected from the group consisting of magnesium, yttrium, ytterbium, cerium, samarium and lanthanum is most preferable.

**[0030]** It is known that the alkaline elements (Group 1a) and those in Groups 4a-2b-3b afford adverse effects upon the wafer process. However, the present inventors found out that the elements, such as, Al ~~in the elements are~~ unfavorable as the ingredients for the corrosion-

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resistive members. That is, if ~~the element~~ the element(s) in Group 3b ~~is~~ is (are) incorporated into the silicon nitride sintered body, the element(s) ~~is~~ is (are) likely to be sputtered and may be attached to the wafers upon receipt of ion bombardment. Such attachment may cause metal contamination or poor etching.